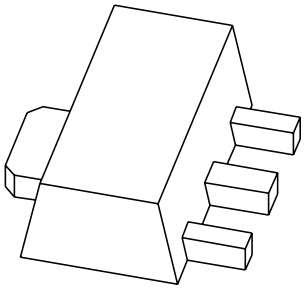
DATA SHEET



BST60; BST61; BST62
PNP Darlington transistors

Product data sheet
Supersedes data of 2001 Feb 20

2004 Dec 09

PNP Darlington transistors BST60; BST61; BST62

FEATURES

- High current (max. 0.5 A)
- Low voltage (max. 80 V)
- Integrated diode and resistor.

APPLICATIONS

- Industrial switching applications such as:
  - Print hammer
  - Solenoid
  - Relay and lamp driving.

DESCRIPTION

PNP Darlington transistor in a SOT89 plastic package.
NPN complements: BST50, BST51 and BST52.

MARKING

TYPE NUMBER	MARKING CODE
BST60	BS1
BST61	BS2
BST62	BS3

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base

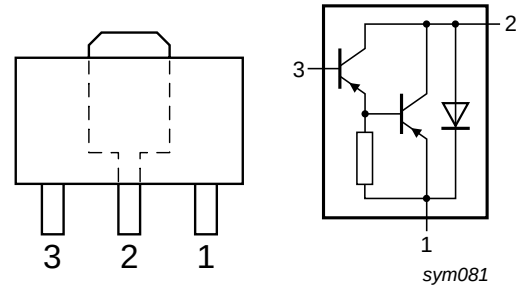


Fig.1 Simplified outline (SOT89) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BST60	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89
BST61			
BST62			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BST60		–	−60	V
	BST61		–	−80	V
	BST62		–	−90	V
V_{CES}	collector-emitter voltage	V_{BE} = 0 V			
	BST60		–	−45	V
	BST61		–	−60	V
	BST62		–	−80	V
V_{EBO}	emitter-base voltage	open collector	–	−5	V
I_C	collector current (DC)		–	−1	A
I_{CM}	peak collector current		–	−2	A
I_B	base current (DC)		–	−100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	1.3	W
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	ambient temperature		−65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm^2. For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook"*.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	96	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point		16	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm^2. For other mounting conditions, see *"Thermal considerations for SOT89 in the General Part of associated Handbook"*.

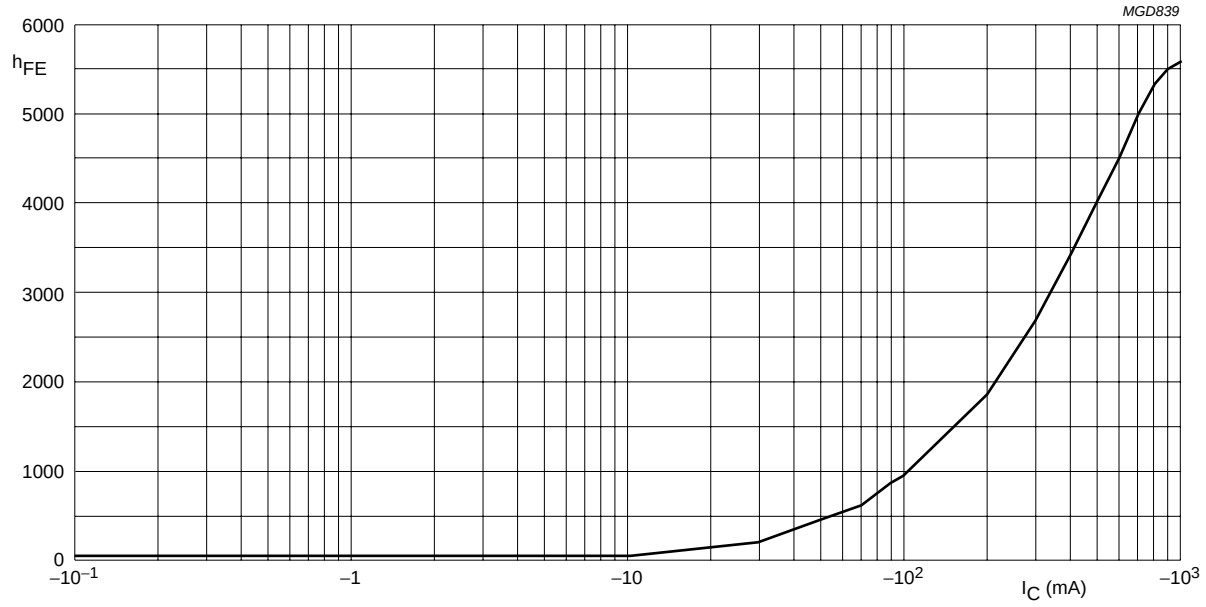
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CES}	collector-emitter cut-off current					
	BST60	V_{BE} = 0 V; V_{CE} = −45 V	−	−	−50	nA
	BST61	V_{BE} = 0 V; V_{CE} = −60 V	−	−	−50	nA
	BST62	V_{BE} = 0 V; V_{CE} = −80 V	−	−	−50	nA
I_{EBO}	emitter-base cut-off current	I_C = 0 A; V_{EB} = −4 V	−	−	−50	nA
h_{FE}	DC current gain	V_{CE} = −10 V; note 1; see Fig.2				
		I_C = −150 mA	1000	−	−	
		I_C = −500 mA	2000	−	−	
V_{CEsat}	collector-emitter saturation voltage	I_C = −500 mA; I_B = −0.5 mA	−	−	−1.3	V
		I_C = −500 mA; I_B = −0.5 mA; T_j = 150 °C	−	−	−1.3	V
V_{BEsat}	base-emitter saturation voltage	I_C = −500 mA; I_B = −0.5 mA	−	−	−1.9	V
f_T	transition frequency	I_C = −500 mA; V_{CE} = −5 V; f = 100 MHz	−	200	−	MHz
Switching times (between 10% and 90% levels); (see Fig.3)						
t_{on}	turn-on time	I_{Con} = −500 mA; I_{Bon} = −0.5 mA; I_{Boff} = 0.5 mA	−	500	−	ns
t_{off}	turn-off time		−	700	−	ns

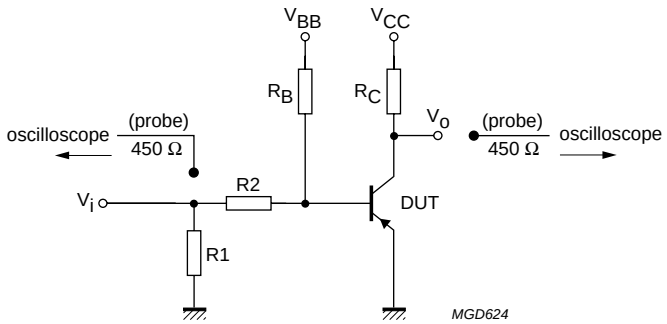
Note

1. Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$.



$V_{CE} = -10$ V.

Fig.2 DC current gain; typical values.

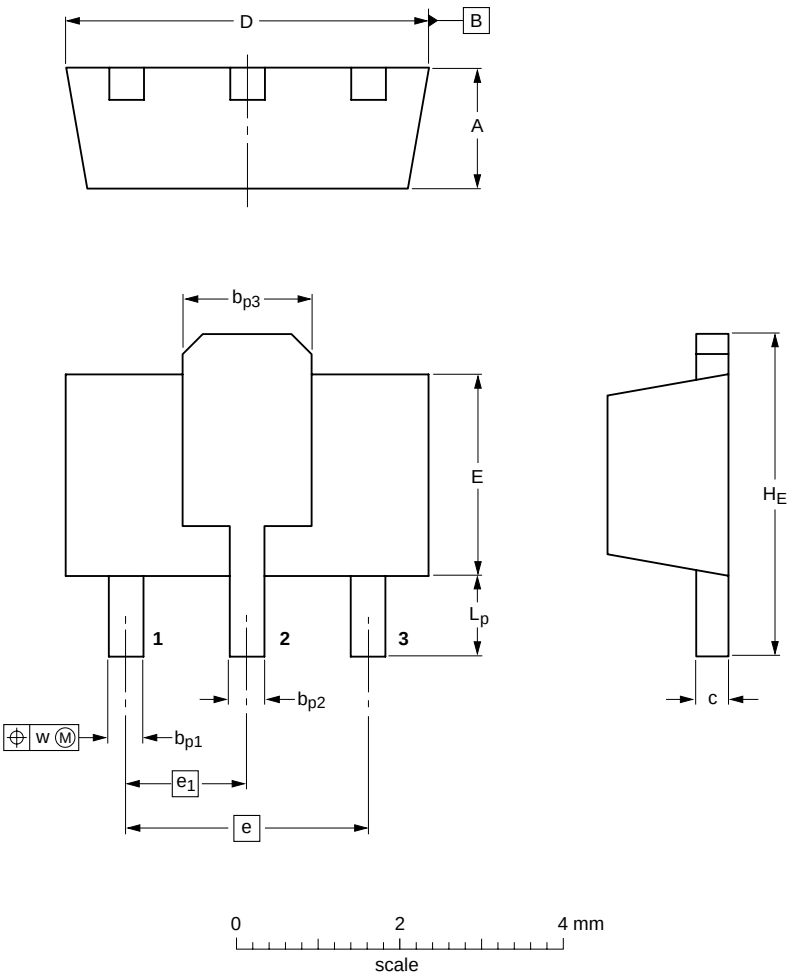


$V_i = -10$ V; T = 200 μs; t_p = 6 μs; $t_r = t_f \leq 3$ ns.
R1 = 56 Ω; R2 = 10 kΩ; R_B = 10 kΩ; R_C = 18 Ω.
V_{BB} = 1.8 V; V_{CC} = −10.7 V.
Oscilloscope: input impedance Z_i = 50 Ω.

Fig.3 Test circuit for switching times.

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads **SOT89**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_{p1}	b_{p2}	b_{p3}	c	D	E	e	e_1	H_E	L_p	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT89		TO-243	SC-62			~~04-08-03~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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